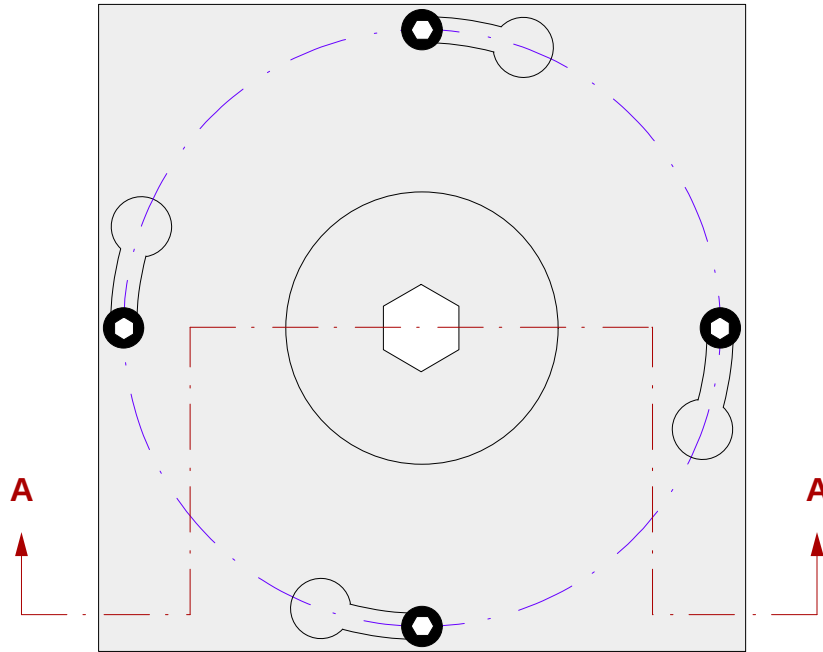


GHz BGA Socket - Direct mount, solderless

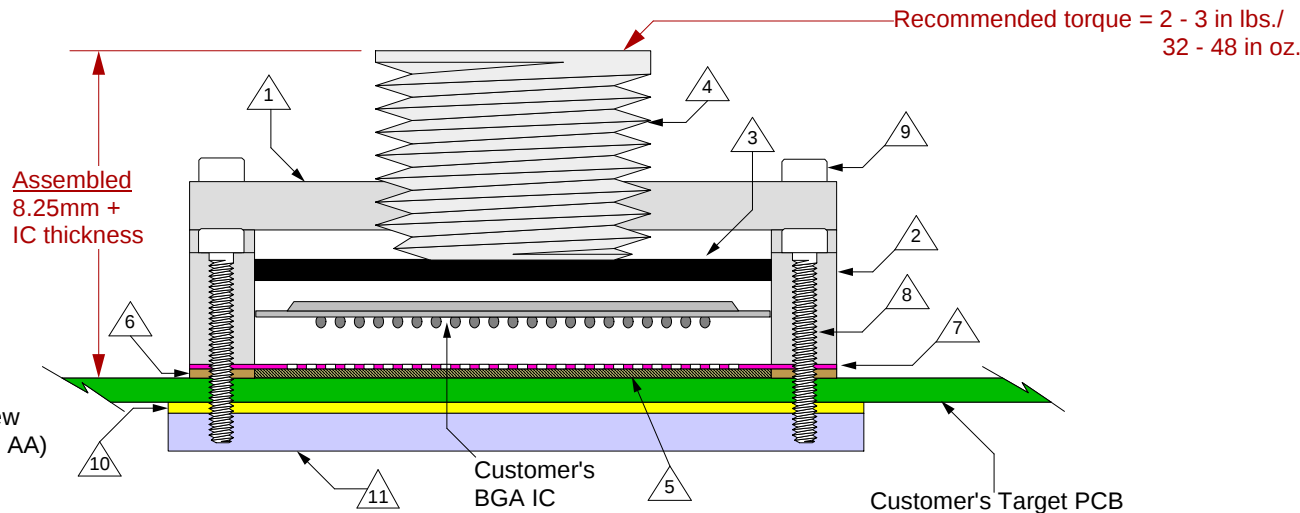
Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Easily removable swivel socket lid

Top View



Side View
(Section AA)



- 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- 5 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- 6 Elastomer Guide: Non-clad FR4. Thickness = 0.475mm.
- 7 Ball Guide: Kapton polyimide.
- 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- 10 Insulation Plate: FR4/G10, Thickness = 1.59mm.
- 11 Backing Plate: Black anodized Aluminum. Thickness = 6.35mm.

SG-BGA-7035 Drawing

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11351 Rupp Drive, Suite 400, Burnsville, MN 55337
Tele: (952) 229-8200
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: D

Drawing: H. Hansen

Date: 1/24/05

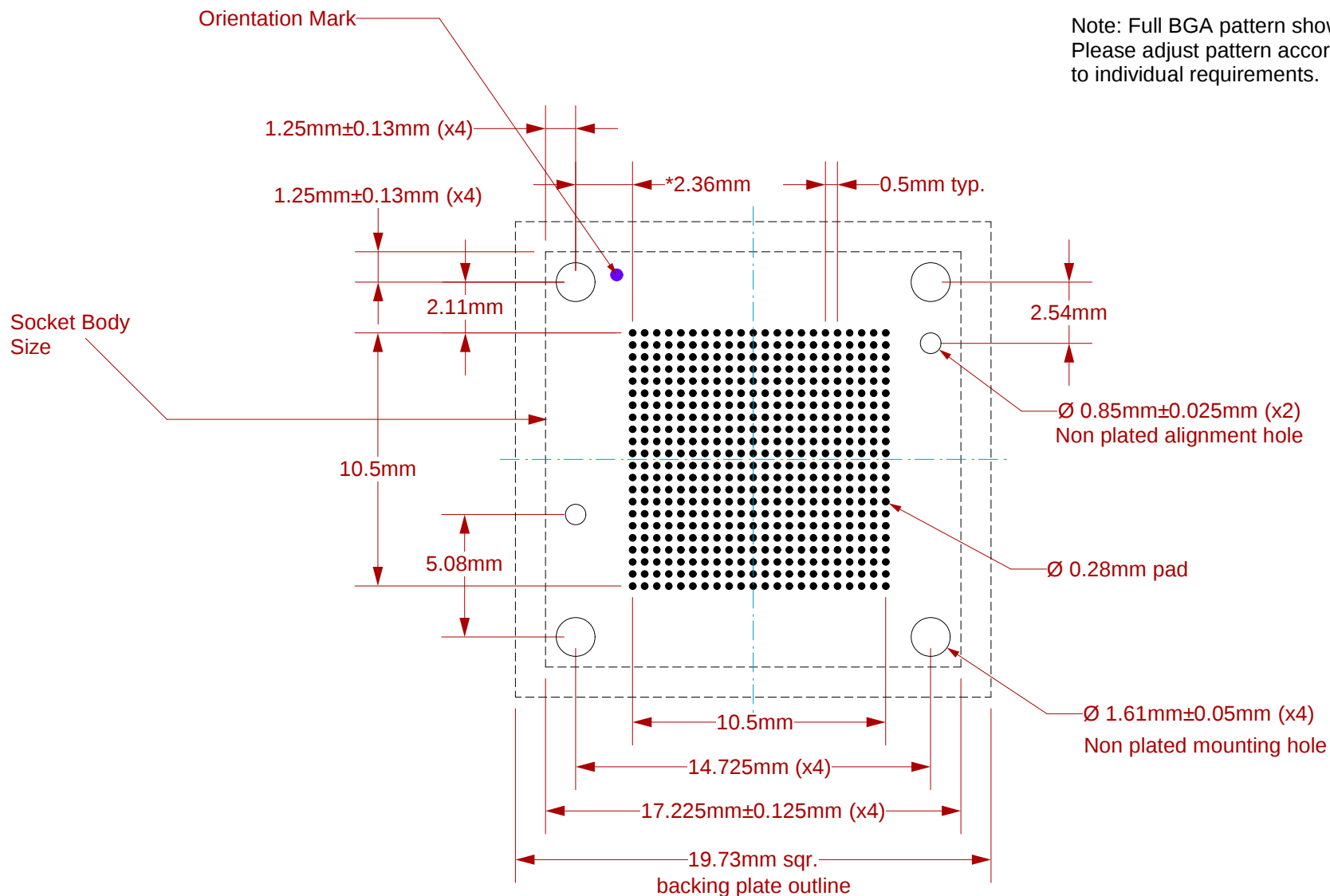
File: SG-BGA-7035 Dwg

Modified: 6/12/09, AE

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: BGA pattern is not symmetrical
with respect to the mounting holes.**

Note: Full BGA pattern shown.
Please adjust pattern according
to individual requirements.



Target PCB Recommendations

Total thickness: 1.6mm min.

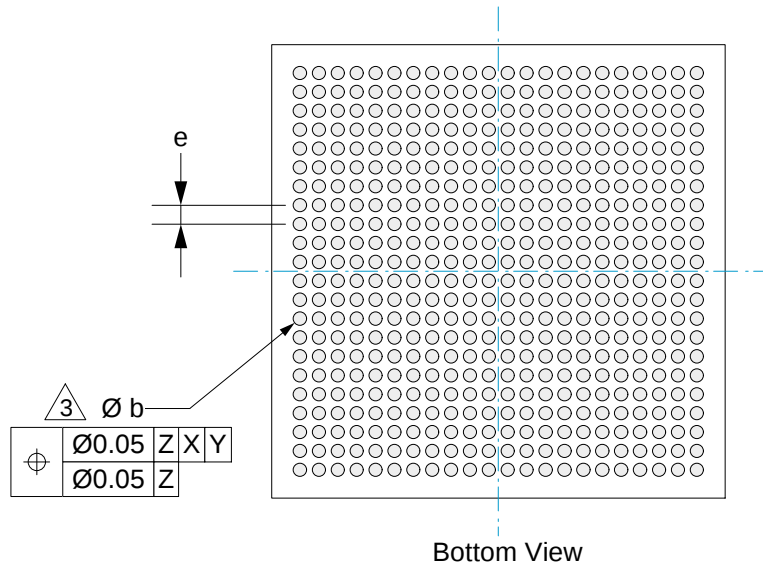
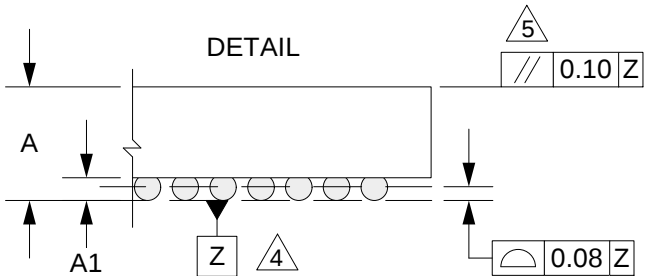
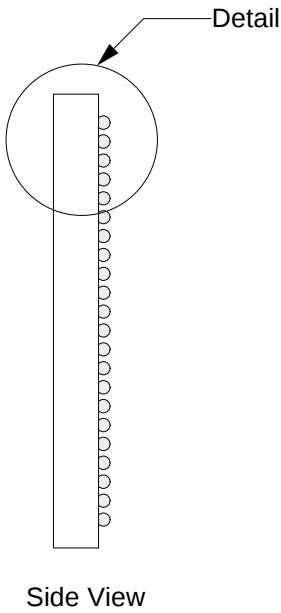
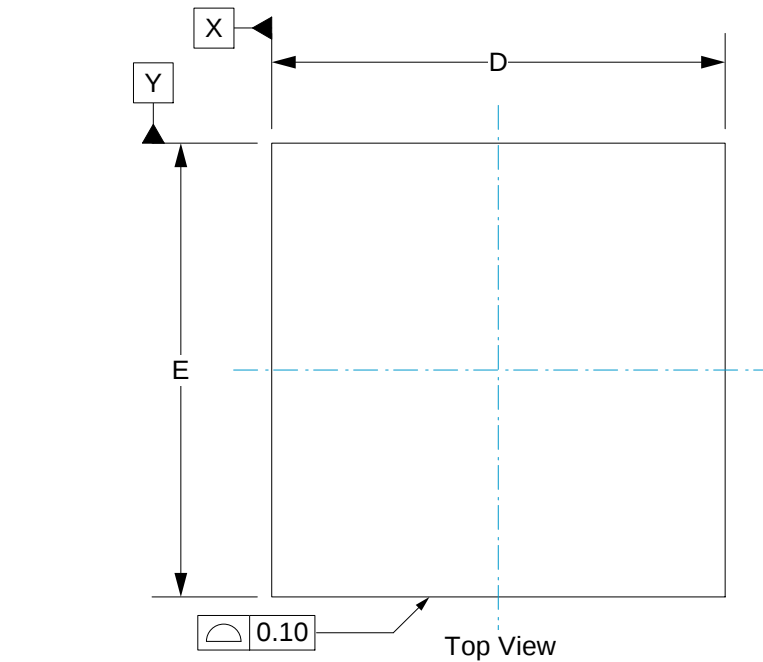
Plating: Gold or Solder finish

PCB Pad height: Same or higher than solder mask

All dimensions are in mm unless stated otherwise

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

SG-BGA-7035 Drawing		Status: Released	Scale: -	Rev: D
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	File: SG-BGA-7035 Dwg		Date: 1/24/05 Modified: 6/12/09, AE	

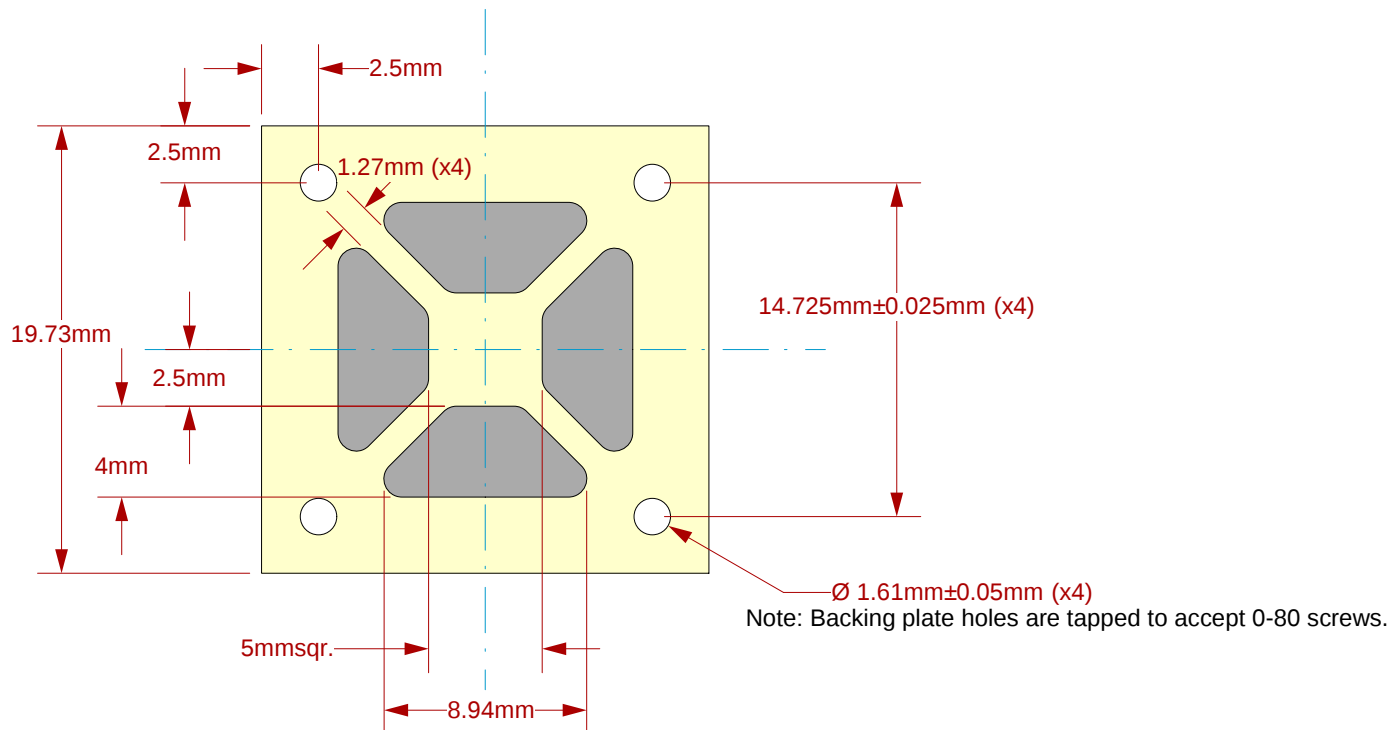


- 1. Dimensions are in millimeters.
- 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

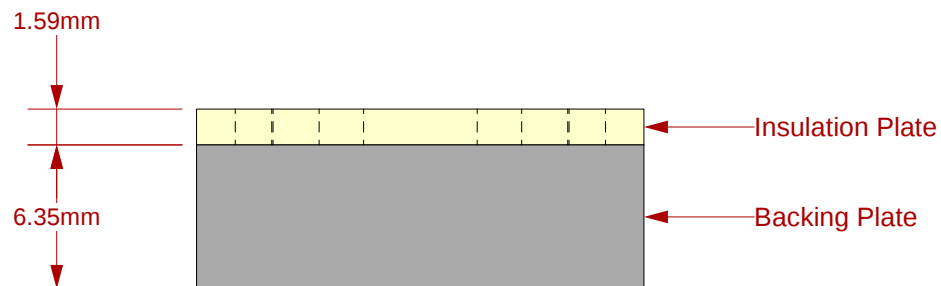
DIM	MIN	MAX
A		1.5
A1	0.2	0.3
b		0.35
D	12.0 BSC	
E	12.0 BSC	
e	0.5 BSC	

22 x 22 array

Top View



Side View



Description: Insulation Plate and Backing Plate

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)

SG-BGA-7035 Drawing		Status: Released	Scale: -	Rev: D
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